

A LOW TEMPERATURE METHOD FOR FABRICATION OF DENSE BORON CARBIDE COMPOSITES

IITM Technology Available for Licensing

Problem Statement

- Processing of Boron carbide is extremely difficult due to its covalent nature and low diffusion coefficient.
- It requires high temperatures ($> 2100\text{ }^{\circ}\text{C}$) and pressures (30-40 MPa) for densification.
- Such processing conditions are expensive and also favor grain coarsening which degrades the mechanical properties.
- There is a need for an improved approach for low temperature sintering processes for fabricating dense B_4C components.

Intellectual Property

- IITM IDF Ref. 1794
- IN 376105- Patent Granted

TRL (Technology Readiness Level)

TRL - 4: Technology validated in lab scale.

Technology Category/ Market

Category-

Advanced materials and Manufacturing

Industry Classification:

- NIC (2008)- 23935-** Manufacture of ceramic laboratory, chemical and industrial products
- NAICS (2022)- 327110-** Pottery, Ceramics, and Plumbing Fixture Manufacturing; **339113-** Bulletproof vests manufacturing
- Applications-** Manufacturing of Neutron absorber, Body Armor material, Blast nozzles, cutting tools, control rods

Market Drivers-

- From 2023 to 2033, the boron carbide market is projected to exhibit a 5.3% CAGR. It is anticipated to rise at a valuation of US\$ 153.9 million in 2023

Research Lab

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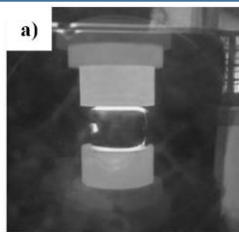


Figure: (a) B_4C 5wt%TiB with punches during sintering stage

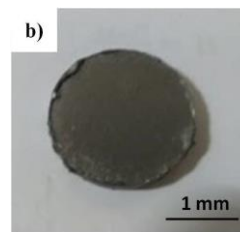


Figure: (b) B_4C sample after sintering B_4C 18 with graphite layer

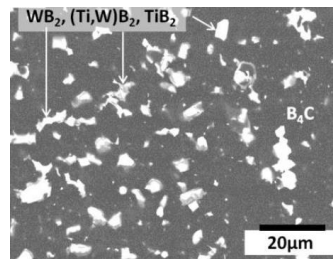


Figure: SEM image of back scattered electron image of polished cross section

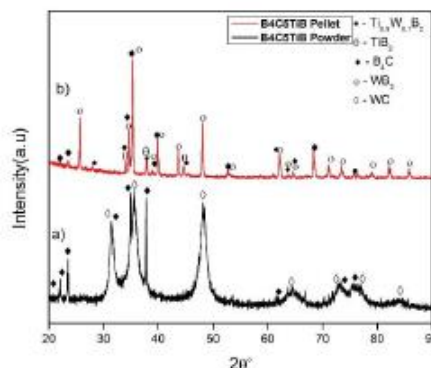


Figure: Graphical representation illustrating XRD patterns of B_4C with 5wt. % Ti-B

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Technology

- 1 The process consists of sintering of B_4C composite at Spark Plasma Sintering (SPS) temperature of $1400^\circ C$ and 50 MPa pressure using mechanically activated Ti-B as sintering aid
- 2 Mechanical activation of Titanium and Boron powder in the ratio 5:95 (by weight) followed by ball milling for 4h for homogeneity and better dispersion
- 3 Spark plasma sintering was carried out at $1400^\circ C$ with a heating rate of $100\ 9^\circ C/min$ and hold time of 10 min at peak temperature with 50 MPa pressure.
- 4 The grain size of the Boron carbide obtained was approximately $15-20\ \mu m$ with no porosity
- 5 The hardness of the sample measured form Vickers micro hardness tester was $\sim 29\ GPa$

Key Features / Value Proposition

- The invention enables fabrication of B_4C composites at $1400^\circ C$ compared to conventional technologies that require a minimum temperature of $1700^\circ C$.
- The calculated theoretical density of the composite is $3.27\ g/cc$ while the measured density of $3.35\ g/cc$ indicates that the achieved density is almost same as the theoretical density. Whereas, prior art processes have reported achievement of only 95-98% of theoretical density.
- Fine grain size and no porosity enhance suitability of the obtained composites for high performance applications.
- The low temperature process reduces fabrication costs without compromising on mechanical properties.

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